Basic information	
2022/0032(COD) COD - Ordinary legislative procedure (ex-codecision procedure) Regulation	Procedure completed
Chips Act **Subject** 3.40.06 Electronics, electrotechnical industries, ICT, robotics **Legislative priorities** Joint Declaration 2022 Joint Declaration 2023-24	

Key players			
European Parliament	**Committee responsible**	**Rapporteur**	**Appointed**
	ITRE Industry, Research and Energy	NICA Dan (S&D)	29/03/2022
		Shadow rapporteur MAYDELL Eva (EPP) GROOTHUIS Bart (Renew) HAHN Henrike (Greens/EFA) NISSINEN Johan (ECR) DAUCHY Marie (ID) BOTENGA Marc (The Left)	
	Committee for opinion	**Rapporteur for opinion**	**Appointed**
	INTA International Trade	BOURGEOIS Geert (ECR)	16/05/2022
	BUDG Budgets	RESSLER Karlo (EPP)	11/03/2022
	ECON Economic and Monetary Affairs	MAYDELL Eva (EPP)	03/03/2022
	IMCO Internal Market and Consumer Protection (Associated committee)	LEITÃO-MARQUES Maria-Manuel (S&D)	31/03/2022
	JURI Legal Affairs (Associated committee)	WÖLKEN Tiemo (S&D)	13/07/2022

Committee for opinion on the legal basis	Rapporteur for opinion	Appointed
JURI Legal Affairs	VOSS Axel (EPP)	01/07/2023

Council of the European Union	
European Commission	

Commission DG	Commissioner
Communications Networks, Content and Technology	BRETON Thierry

European Economic and Social Committee

Key events

Date	Event	Reference	Summary
09/02/2022	Legislative proposal published	COM(2022)0046	Summary
07/03/2022	Committee referral announced in Parliament, 1st reading		
07/07/2022	Referral to associated committees announced in Parliament		
24/01/2023	Vote in committee, 1st reading		
24/01/2023	Committee decision to open interinstitutional negotiations with report adopted in committee		
31/01/2023	Committee report tabled for plenary, 1st reading	A9-0014/2023	Summary
13/02/2023	Committee decision to enter into interinstitutional negotiations announced in plenary (Rule 71)		
15/02/2023	Committee decision to enter into interinstitutional negotiations confirmed by plenary (Rule 71)		
23/05/2023	Approval in committee of the text agreed at 1st reading interinstitutional negotiations	GEDA/A/(2023)003327	
11/07/2023	Decision by Parliament, 1st reading	T9-0266/2023	Summary
11/07/2023	Results of vote in Parliament		
11/07/2023	Debate in Parliament		
25/07/2023	Act adopted by Council after Parliament's 1st reading		
13/09/2023	Final act signed		
18/09/2023	Final act published in Official Journal		

Technical information

Procedure reference	2022/0032(COD)

Procedure type	COD - Ordinary legislative procedure (ex-codecision procedure)
Procedure subtype	Legislation
Legislative instrument	Regulation
Legal basis	Rules of Procedure EP 41 Rules of Procedure EP 57_o Treaty on the Functioning of the European Union TFEU 183 Treaty on the Functioning of the European Union TFEU 182-p1 Treaty on the Functioning of the European Union TFEU 173-p3 Treaty on the Functioning of the European Union TFEU 114
Other legal basis	Rules of Procedure EP 165
Mandatory consultation of other institutions	European Economic and Social Committee
Stage reached in procedure	Procedure completed
Committee dossier	ITRE/9/08359

Documentation gateway

European Parliament

Document type	Committee	Reference	Date	Summary
Committee draft report		PE731.655	19/09/2022	
Amendments tabled in committee		PE737.266	18/10/2022	
Amendments tabled in committee		PE737.348	18/10/2022	
Amendments tabled in committee		PE737.359	18/10/2022	
Committee opinion	ECON	PE732.593	15/11/2022	
Committee opinion	BUDG	PE734.234	18/11/2022	
Committee opinion	JURI	PE736.697	01/12/2022	
Committee opinion	INTA	PE735.744	05/12/2022	
Committee opinion	IMCO	PE735.490	14/12/2022	
Committee report tabled for plenary, 1st reading/single reading		A9-0014/2023	31/01/2023	Summary
Specific opinion	JURI	PE750.045	27/06/2023	
Text adopted by Parliament, 1st reading/single reading		T9-0266/2023	11/07/2023	Summary

Council of the EU

Document type	Reference	Date	Summary
Coreper letter confirming interinstitutional agreement	GEDA/A/(2023)003327	10/05/2023	
Draft final act	00028/2023/LEX	13/09/2023	

European Commission

Document type	Reference	Date	Summary
	COM(2022)0046		

Legislative proposal		09/02/2022	Summary
Commission response to text adopted in plenary	SP(2023)459	30/10/2023	

National parliaments

Document type	Parliament /Chamber	Reference	Date	Summary
Contribution	CZ_SENATE	COM(2022)0046	25/05/2022	

Other institutions and bodies

Institution/body	Document type	Reference	Date	Summary
EESC	Economic and Social Committee: opinion, report	CES1354/2022	15/06/2022	
CofR	Committee of the Regions: opinion	CDR1960/2022	12/10/2022	

Additional information

Source	Document	Date
EP Research Service	Briefing	12/07/2022
European Commission	EUR-Lex	

Meetings with interest representatives published in line with the Rules of Procedure

Rapporteurs, Shadow Rapporteurs and Committee Chairs

Transparency

Name	Role	Committee	Date	Interest representatives
RESSLER Karlo	Rapporteur for opinion	BUDG	06/12/2023	Applied Materials
GÁLVEZ Lina	Rapporteur	ITRE	06/06/2023	IQM Quantum Computers
GROOTHUIS Bart	Shadow rapporteur	ITRE	31/03/2023	NXP Semiconductors Netherlands B.V.
GROOTHUIS Bart	Shadow rapporteur	ITRE	31/03/2023	Nexperia
GROOTHUIS Bart	Shadow rapporteur	ITRE	23/03/2023	ESIA
GROOTHUIS Bart	Shadow rapporteur	ITRE	23/03/2023	Digital Europe
GROOTHUIS Bart	Shadow rapporteur	ITRE	22/03/2023	ESIA
GROOTHUIS Bart	Shadow rapporteur	ITRE	20/03/2023	Digital Europe
GROOTHUIS Bart	Shadow rapporteur	ITRE	15/03/2023	Vereniging VNO-NCW
GROOTHUIS Bart	Shadow rapporteur	ITRE	15/03/2023	ESIA

GROOTHUIS Bart	Shadow rapporteur	ITRE	15/03/2023	ASML Netherlands B.V.
GROOTHUIS Bart	Shadow rapporteur	ITRE	08/03/2023	Institut Montaigne
WÖLKEN Tiemo	Rapporteur	JURI	07/03/2023	Ständige Vertretung der Bundesrepublik Deutschland
NICA Dan	Rapporteur	ITRE	06/03/2023	Infineon Technologies AG
RESSLER Karlo	Rapporteur for opinion	BUDG	01/03/2023	Interuniversity Microelectronics Centre (IMEC)
RESSLER Karlo	Rapporteur for opinion	BUDG	01/03/2023	Institut Ruđer Bošković (IRB)
RESSLER Karlo	Rapporteur for opinion	BUDG	01/03/2023	University of Zagreb, Faculty of Electrical Engineering and Computing
RESSLER Karlo	Rapporteur for opinion	BUDG	01/03/2023	Institute of Physics Zagreb
RESSLER Karlo	Rapporteur for opinion	BUDG	23/02/2023	Uber
RESSLER Karlo	Rapporteur for opinion	BUDG	22/02/2023	Stanford University
RESSLER Karlo	Rapporteur for opinion	BUDG	21/02/2023	Cisco Systems Inc. META NASA AMES Stanford Social Media Lab and Cyber Policy Center
MAYDELL Eva	Shadow rapporteur for opinion	ECON	18/02/2023	NXP Semiconductors Netherlands B.V.
GROOTHUIS Bart	Shadow rapporteur	ITRE	15/02/2023	ASML Netherlands B.V.
GROOTHUIS Bart	Shadow rapporteur	ITRE	24/01/2023	Vereniging VNO-NCW
GROOTHUIS Bart	Shadow rapporteur	ITRE	19/01/2023	Austrian Institute of Technology GmbH
WARBORN Jörgen	Shadow rapporteur	INTA	10/01/2023	Sveriges EU-representation
HAHN Henrike	Shadow rapporteur	ITRE	20/12/2022	Intel Corporation
GROOTHUIS Bart	Shadow rapporteur	ITRE	19/12/2022	Digital Europe
GROOTHUIS Bart	Shadow rapporteur	ITRE	15/12/2022	Nexperia
GROOTHUIS Bart	Shadow rapporteur	ITRE	14/12/2022	NXP Semiconductors Netherlands B.V.
GROOTHUIS Bart	Shadow rapporteur	ITRE	13/12/2022	Vereniging VNO-NCW
GROOTHUIS Bart	Shadow rapporteur	ITRE	12/12/2022	Intel Corporation
BOURGEOIS Geert	Rapporteur for opinion	INTA	12/12/2022	Intel Corporation
NICA Dan	Rapporteur	ITRE	12/12/2022	Merck INTEL Qualcomm CEA LETI
GROOTHUIS Bart	Shadow rapporteur	ITRE	09/12/2022	VDL Groep
GROOTHUIS Bart	Shadow rapporteur	ITRE	08/12/2022	Quantum Delta NL
LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	07/12/2022	Applied Materials
GROOTHUIS Bart	Shadow rapporteur	ITRE	06/12/2022	Netherlands Permanent Representation

LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	01/12/2022	SAFRAN
GROOTHUIS Bart	Shadow rapporteur	ITRE	29/11/2022	Brussels Times
GROOTHUIS Bart	Shadow rapporteur	ITRE	16/11/2022	Quantum Flagship Community Network
RESSLER Karlo	Rapporteur for opinion	BUDG	15/11/2022	EuroNavigator Public Affairs
GROOTHUIS Bart	Shadow rapporteur	ITRE	15/11/2022	US Government
LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	09/11/2022	ResMed
GROOTHUIS Bart	Shadow rapporteur	ITRE	09/11/2022	US Government
LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	08/11/2022	SAFRAN
GROOTHUIS Bart	Shadow rapporteur	ITRE	08/11/2022	Belgium Permanent Representation
NICA Dan	Rapporteur	ITRE	08/11/2022	ResMed
LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	07/11/2022	Orgalim – Europe's Technology Industries
GROOTHUIS Bart	Shadow rapporteur	ITRE	07/11/2022	RedMed
GROOTHUIS Bart	Shadow rapporteur	ITRE	04/11/2022	Digital Europe
BOURGEOIS Geert	Rapporteur for opinion	INTA	25/10/2022	Voka - Vlaams Netwerk van Ondernemingen
RESSLER Karlo	Rapporteur for opinion	BUDG	19/10/2022	The British Chambers of Commerce
LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	13/10/2022	DIGITALEUROPE
ANSIP Andrus	Shadow rapporteur for opinion	IMCO	13/10/2022	MedTech Europe
GROOTHUIS Bart	Shadow rapporteur	ITRE	11/10/2022	Netherlands Permanent Representation
GROOTHUIS Bart	Shadow rapporteur	ITRE	11/10/2022	ASML Netherlands B.V.
LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	10/10/2022	ASML Netherlands B.V.
LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	10/10/2022	DIGITALEUROPE
GROOTHUIS Bart	Shadow rapporteur	ITRE	07/10/2022	Atlantic Council of the United States, Inc
WARBORN Jörgen	Shadow rapporteur for opinion	INTA	05/10/2022	Silex Microsystems AB
WARBORN Jörgen	Shadow rapporteur for opinion	INTA	05/10/2022	Svenskt Näringsliv
WÖLKEN Tiemo	Rapporteur for opinion	JURI	05/10/2022	Qualcomm
WARBORN Jörgen	Shadow rapporteur for opinion	INTA	04/10/2022	Kommerskollegium
WÖLKEN Tiemo	Rapporteur for opinion	JURI	04/10/2022	Intel
GROOTHUIS Bart	Shadow rapporteur	ITRE	04/10/2022	AIR LIQUIDE
	Shadow rapporteur for			

VANDENKENDELAERE Tom	opinion	IMCO	02/10/2022	Belgan
VANDENKENDELAERE Tom	Shadow rapporteur for opinion	IMCO	30/09/2022	ASML Netherlands B.V.
WÖLKEN Tiemo	Rapporteur for opinion	JURI	29/09/2022	AENEAS Inside EPoSS
GROOTHUIS Bart	Shadow rapporteur	ITRE	29/09/2022	The LEGO Group
GROOTHUIS Bart	Shadow rapporteur	ITRE	29/09/2022	Netherlands Permanent Representation
WÖLKEN Tiemo	Rapporteur for opinion	JURI	28/09/2022	MedTech Europe
GROOTHUIS Bart	Shadow rapporteur	ITRE	28/09/2022	SNV
WÖLKEN Tiemo	Rapporteur for opinion	JURI	26/09/2022	Continental AG
HAHN Henrike	Shadow rapporteur	ITRE	22/09/2022	SEMIKRON
HAHN Henrike	Shadow rapporteur	ITRE	22/09/2022	Osram
PEKKARINEN Mauri	Shadow rapporteur for opinion	BUDG	22/09/2022	ASM Microchemistry Oy
HAHN Henrike	Shadow rapporteur	ITRE	21/09/2022	nextnano GmbH
HAHN Henrike	Shadow rapporteur	ITRE	21/09/2022	Infineon Technologies AG
HAHN Henrike	Shadow rapporteur	ITRE	20/09/2022	B-Horizon
HAHN Henrike	Shadow rapporteur	ITRE	20/09/2022	NXP Semiconductors Netherlands B.V.
GROOTHUIS Bart	Shadow rapporteur	ITRE	20/09/2022	The Hague Centre for Strategic Studies
GROOTHUIS Bart	Shadow rapporteur	ITRE	19/09/2022	Digital Europe
GROOTHUIS Bart	Shadow rapporteur	ITRE	16/09/2022	Micron Technology Inc.
LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	14/09/2022	Intel Corporation
RESSLER Karlo	Rapporteur for opinion	BUDG	13/09/2022	Intel Corporation
CORMAND David	Shadow rapporteur for opinion	IMCO	08/09/2022	Stiftung Neue Verantwortung e.V.
RESSLER Karlo	Rapporteur for opinion	BUDG	08/09/2022	IPC International, Inc.
GROOTHUIS Bart	Shadow rapporteur	ITRE	08/09/2022	Kalray SA
NICA Dan	Rapporteur	ITRE	06/09/2022	European Forum for Manufacturing
LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	05/09/2022	MedTech Europe
GROOTHUIS Bart	Shadow rapporteur	ITRE	05/09/2022	Eindhoven Technical University
RINZEMA Catharina	Shadow rapporteur for opinion	INTA	31/08/2022	ESIA
PEKKARINEN Mauri	Shadow rapporteur for opinion	BUDG	11/08/2022	Picosun
	Shadow rapporteur for			

PEKKARINEN Mauri	opinion	BUDG	11/08/2022	Representative of Taiwan
ANGEL Marc	Shadow rapporteur for opinion	ECON	14/07/2022	Stiftung Neue Verantwortung e.V.
WARBORN Jörgen	Shadow rapporteur for opinion	INTA	13/07/2022	Infineon Technologies AG NXP Semiconductors Netherlands B.V. STMicroelectronics France ESIA Robert Bosch
LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	13/07/2022	IMEC
NICA Dan	Rapporteur	ITRE	13/07/2022	British Chamber of Commerce | EU & Belgium
GROOTHUIS Bart	Shadow rapporteur	ITRE	06/07/2022	AmCham
GROOTHUIS Bart	Shadow rapporteur	ITRE	05/07/2022	MENTA
ANGEL Marc	Shadow rapporteur for opinion	ECON	01/07/2022	FEDIL - The Voice of Luxembourg's Industry IEE S.A.
GROOTHUIS Bart	Shadow rapporteur	ITRE	30/06/2022	DIGITALEUROPE
GROOTHUIS Bart	Shadow rapporteur	ITRE	30/06/2022	EUROPE'S MEDIALAB (Fondation EURACTIV)
GROOTHUIS Bart	Shadow rapporteur	ITRE	29/06/2022	IPC International, Inc.
GROOTHUIS Bart	Shadow rapporteur	ITRE	29/06/2022	AMD
GROOTHUIS Bart	Shadow rapporteur	ITRE	29/06/2022	ASML Netherlands B.V.
ANGEL Marc	Shadow rapporteur for opinion	ECON	28/06/2022	Stiftung Neue Verantwortung e.V.
GROOTHUIS Bart	Shadow rapporteur	ITRE	28/06/2022	DIGITALEUROPE
ANGEL Marc	Shadow rapporteur for opinion	ECON	28/06/2022	European Semiconductor Industry Association
GROOTHUIS Bart	Shadow rapporteur	ITRE	23/06/2022	Neth-ER
NICA Dan	Rapporteur	ITRE	20/06/2022	EESC- European Economic and Social Committee
GROOTHUIS Bart	Shadow rapporteur	ITRE	16/06/2022	IMEC
NICA Dan	Rapporteur	ITRE	16/06/2022	IMEC
ANSIP Andrus	Shadow rapporteur for opinion	IMCO	14/06/2022	Applied Materials
MAYDELL Eva	Rapporteur	ITRE	13/06/2022	JEDI Exponential
VANDENKENDELAERE Tom	Shadow rapporteur for opinion	IMCO	10/06/2022	IMEC
GROOTHUIS Bart	Shadow rapporteur	ITRE	07/06/2022	Intel
NICA Dan	Rapporteur	ITRE	07/06/2022	INTEL
NICA Dan	Rapporteur	ITRE	07/06/2022	Taiwan Ambassy representative
GROOTHUIS Bart	Shadow rapporteur	ITRE	01/06/2022	ESIA, NXP, Peopol, ST Microelectronics
STEGRUD Jessica	Shadow rapporteur	ITRE	01/06/2022	Svenskt Näringsliv

PEKKARINEN Mauri	Shadow rapporteur for opinion	BUDG	01/06/2022	Business Finland The Ministry of Economic Affairs and Employment of Finland
NICA Dan	Rapporteur	ITRE	31/05/2022	Forschunzentrum Julich
KUMPULA-NATRI Miapetra	Shadow rapporteur	ITRE	31/05/2022	Intel Corporation
STEGRUD Jessica	Shadow rapporteur	ITRE	30/05/2022	Teknikföretagen
GROOTHUIS Bart	Shadow rapporteur	ITRE	25/05/2022	ASMI
LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	25/05/2022	Stiftung Neue Verantwortung e.V.
DE BASSO Ilan	Shadow rapporteur for opinion	BUDG	25/05/2022	Volvo Cars Aurobay
GROOTHUIS Bart	Shadow rapporteur	ITRE	24/05/2022	Applied Materials
DE BASSO Ilan	Shadow rapporteur for opinion	BUDG	24/05/2022	Husqvarna AB
GROOTHUIS Bart	Shadow rapporteur	ITRE	18/05/2022	QUALCOMM Incorporated
RESSLER Karlo	Rapporteur for opinion	BUDG	17/05/2022	ASML Netherlands B.V. AT&T, Inc. Applied Materials DIGITALEUROPE Infineon Technologies AG Intel Corporation NOVE NXP Semiconductors Netherlands B.V. Samsung Electronics Europe Stenström Consulting
LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	16/05/2022	Giesecke+Devrient
NICA Dan	Rapporteur	ITRE	13/05/2022	AmCham EU
NICA Dan	Rapporteur	ITRE	11/05/2022	CoR- Committee of the Regions
MAYDELL Eva	Rapporteur	ITRE	05/05/2022	Qualcomm Communications SARL
RESSLER Karlo	Rapporteur for opinion	BUDG	03/05/2022	AT&T, Inc.
LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	02/05/2022	DIGITALEUROPE
PEKKARINEN Mauri	Shadow rapporteur for opinion	REGI	29/04/2022	Aalto University Oulu University University of Helsinki Academy of Finland
PEKKARINEN Mauri	Shadow rapporteur for opinion	BUDG	29/04/2022	Confederation of Finnish Industries EK Technology Industries of Finland (Teknologiateollisuus ry) Murata Picosun
LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	28/04/2022	Applied Materials
NICA Dan	Rapporteur	ITRE	28/04/2022	Forum Europe
RINZEMA Catharina	Shadow rapporteur for opinion	INTA	27/04/2022	ASML Netherlands B.V.

DE BASSO Ilan	Shadow rapporteur	BUDG	27/04/2022	Teknikföretagen
ANGEL Marc	Shadow rapporteur for opinion	ECON	27/04/2022	Applied Materials NOVE
NICA Dan	Rapporteur	ITRE	27/04/2022	Applied Materials
NICA Dan	Rapporteur	ITRE	27/04/2022	STMicroelectronics France
NICA Dan	Rapporteur	ITRE	27/04/2022	NXP Semiconductors Netherlands B.V.
NICA Dan	Rapporteur	ITRE	27/04/2022	The European Semiconductor Industry Association - ESIA
LEITÃO-MARQUES Maria-Manuel	Rapporteur for opinion	IMCO	26/04/2022	European Semiconductor Industry Association
RESSLER Karlo	Rapporteur for opinion	BUDG	26/04/2022	Applied Materials
PEKKARINEN Mauri	Shadow rapporteur for opinion	BUDG	26/04/2022	NOVE
GROOTHUIS Bart	Shadow rapporteur	ITRE	22/04/2022	ASML Netherlands B.V.

Other Members

Transparency		
Name	**Date**	**Interest representatives**
SKYTTEDAL Sara	29/06/2023	Stiftelsen Fritt Näringsliv
PEKKARINEN Mauri	31/05/2023	Tampere region EU Office
VANDENKENDELAERE Tom	31/05/2023	IMEC
PEKKARINEN Mauri	28/03/2023	City of Tampere
VAN BREMPT Kathleen	01/12/2022	IMEC
SANT Alfred	13/10/2022	STMicroelectronics France
SANT Alfred	28/09/2022	Malta enterprise
HAHN Svenja	14/09/2022	Intel Corporation

Final act	
Regulation 2023/1781 OJ L 229 18.09.2023, p. 0001	Summary

Chips Act

2022/0032(COD) - 09/02/2022 - Legislative proposal

PURPOSE: to establish a framework of measures for strengthening the semiconductor ecosystem in the Union (Chips Act).

PROPOSED ACT: Regulation of the European Parliament and of the Council.

ROLE OF THE EUROPEAN PARLIAMENT: the European Parliament decides in accordance with the ordinary legislative procedure and on an equal footing with the Council.

BACKGROUND: within the past year, Europe has witnessed disruptions in the supply of chips, causing shortages across multiple economic sectors and potentially serious societal consequences. Many European sectors, including automotive, energy, communication and health as well as strategic sectors such as defence, security, and space are under threat by such supply disruptions.

The current **supply shortage** is a symptom of permanent and serious structural deficiencies in the Union’s semiconductor value and supply chain. The global semiconductor shortage has exposed **European dependency** on supply from a limited number of companies and geographies, and its vulnerability to third country export restrictions and other disruptions in the present geopolitical context.

The proposal aims at reaching the strategic objective of **increasing the resilience of Europe’s semiconductor ecosystem and increasing its global market share**. It also aims at facilitating early adoption of new chips by European industry and increasing its competitiveness.

The European Chips Strategy is articulated around five strategic objectives. Europe should:

(1) strengthen its research and technology leadership;

(2) build and reinforce its own capacity to innovate in the design, manufacturing and packaging of advanced chips, and turn them into commercial products;

(3) put in place an adequate framework to increase substantially its production capacity by 2030;

(4) address the acute skills shortage, attract new talent and support the emergence of a skilled workforce;

(5) develop an in-depth understanding of global semiconductor supply chains.

CONTENT: the proposed Regulation establishes a **framework for strengthening the semiconductor sector at EU level**, including the following measures:

(1) Set up the Chips for Europe Initiative which is designed to strengthen the Union's competitiveness, resilience and innovation capacity. This initiative aims to support large-scale technological capacity building across the Union in existing, advanced and new generation semiconductor technologies. The initiative will:

- set up an **innovative virtual design platform** to strengthen Europe's design capacity, which will be accessible under open, non-discriminatory and transparent conditions;

- support **pilot lines** that provide third parties with the means to test, validate and further develop the products they design under open, transparent and non-discriminatory conditions;

- contribute to the development of advanced technologies and engineering capacities to accelerate the innovative development of quantum chips;

- support a **network of competence centres** across the EU that will provide expertise to stakeholders and improve their skills;

- support the activities of the **Chips Fund** which will facilitate access to finance for start-ups to help them mature their innovations and attract investors.

The Regulation provides for a procedural framework to facilitate combined funding from Member States, investment without prejudice with State aid rules, the Union budget and private investment.

(2) A new framework to ensure security of supply: to attract investment and enhance production capacity in semiconductor manufacturing, advanced packaging, testing and assembly via first-of-a-kind integrated production facilities and open EU Foundries.

In particular, the proposal sets out criteria to facilitate the implementation of specific projects that contribute to the security of supply of semiconductors in the Union. Facilities that are recognised by the Commission as EU integrated production facilities or EU open foundries will be considered as contributing to the security of supply of semiconductors in the Union and thus as serving the public interest.

(3) The establishment of a coordination mechanism between Member States and the Commission for monitoring semiconductor supply and responding to crisis situations in the event of semiconductor shortages.

This mechanism will strengthen collaboration with and across Member States, monitor the supply of semiconductors, estimate demand, anticipate shortages, trigger the activation of a crisis stage and act through a dedicated toolbox of measures.

Budgetary impact

The EU budget will support the Chips for Europe initiative with a total amount of up to **EUR 3.3 billion**, of which EUR 1.65 billion through the Horizon Europe programme and EUR 1.65 billion through the Digital Europe programme. Of this total, EUR 2.875 billion will be implemented through the Chips Joint Undertaking, EUR 125 million through InvestEU and EUR 300 million through the Connecting Europe Facility (CEF).

Chips Act

2022/0032(COD) - 11/07/2023 - Text adopted by Parliament, 1st reading/single reading

The European Parliament adopted by 587 votes to 10, with 38 abstentions, a legislative resolution on the proposal for a regulation of the European Parliament and of the Council establishing a framework of measures for strengthening Europe's semiconductor ecosystem and amending Regulation (EU) 2021/694 (Chips Act).

The European Parliament's position adopted at first reading under the ordinary legislative procedure amends the Commission proposal as follows:

Purpose and general objectives

The Regulation aims to establish a framework for **strengthening the semiconductor ecosystem at EU level**. Its first general objective is to ensure that the conditions necessary for the Union's competitiveness and capacity for innovation are met and to guarantee the industry's adaptation to structural change. The second, complementary, general objective is to improve the functioning of the internal market by establishing a uniform EU legal framework to increase resilience and security of supply in the EU in the field of semiconductor technologies.

Chips for Europe initiative

The Initiative aims to achieve **large-scale technological capacity building** and support related research and innovation activities throughout the Union’s semiconductor value chain. It should also contribute to the achievement of the green and digital transitions, in particular by reducing the climate impact of electronic systems, improving the sustainability of next-generation chips and strengthening the circular economy processes, contribute to **quality jobs** within the semiconductor ecosystem and address security-by-design principles, which provide protection against cybersecurity threats.

The 5 operational objectives of the initiative may include capacity-building activities and related research and innovation activities. All capacity-building activities will be funded under the Digital Europe programme and related research and innovation activities will be funded under Horizon Europe.

European chips infrastructure consortiums

For the purpose of implementing actions funded under the Initiative, a legal entity may be established in the form of a European chips infrastructure consortium (ECIC). An ECIC should be established by at least three members (founding members), namely Member States, or public or private legal entities from at least three Member States, or a combination thereof, with a view to achieving broad representation across the Union.

Application for status as integrated production facility or open EU foundry

Integrated Production Facilities and Open Foundries in the EU are pioneering facilities for semiconductor manufacturing. Their creation should have a **clear positive impact**, extending beyond the individual company or Member State, on the EU semiconductor value chain in the medium to long term to ensure the security of supply and resilience of the semiconductor ecosystem, including the **growth of start-ups and SMEs**, contributing to the EU's green and digital transitions.

They will (i) invest in the Union in continued innovation with a view to achieving concrete advances in semiconductor technology or preparing next-generation technologies; (ii) support the Union talent pipeline by developing and deploying educational and skills training and by increasing the pool of qualified and skilled workforce.

The Commission may award a **label of ‘design centre of excellence’** to design centres established in the Union that significantly enhance the Union’s capabilities in innovative chip design through their service offerings or through the development, promotion and strengthening of design skills and capabilities.

Fast-tracking of permit-granting procedures

Member States should ensure that administrative applications related to the planning, construction and operation of integrated production facilities and open EU foundries are processed in an efficient, transparent and timely manner. To that end, all national authorities concerned should ensure that the most rapid treatment legally possible is given to these applications in a manner that fully respects national law and procedure. Where such a status exists in national law, integrated production facilities and open EU foundries should be allocated the **status of the highest national significance** possible and be treated as such in permit-granting processes.

Strategic mapping of the Union’s semiconductor sector

The Commission should carry out a strategic mapping of the Union’s semiconductor sector which will provide an **analysis of the Union’s strengths and weaknesses** in the global semiconductor sector and identify factors such as: (i) key products and critical infrastructures in the internal market that are depending on the supply of semiconductors; (ii) main user industries in the Union and their current and expected needs and dependencies; (iii) the technological characteristics, the dependencies on third-country technology and providers, and bottlenecks of the Union’s semiconductor sector including access to inputs; (iv) current and expected needs for skills and effective access to qualified workforce in the semiconductor sector.

Alerts and preventive action

The Commission, in consultation with the European Semiconductor Council, will regularly monitor the semiconductor value chain in order to identify factors that could disrupt, jeopardise or adversely affect the supply of or trade in semiconductors.

If a competent national authority becomes aware of a risk of serious disruption to the supply of semiconductors, it should alert the Commission without delay. Where the **crisis stage** is activated, the Commission may, upon the request of two or more Member States, act as a central purchasing body on behalf of all Member States willing to participate for their public procurement of crisis-relevant products for critical sectors.

Digital Europe Programme (budget)

The financial envelope for the implementation of the Programme for the period from 1 January 2021 to 31 December 2027 should be **EUR 8 168 000 000** in current prices, broken down as follows:

- EUR 2 019 914 000 for Specific Objective 1 – High Performance Computing;

- EUR 1 663 956 000 for Specific Objective 2 – Artificial Intelligence;

- EUR 1 399 566 000 for Specific Objective 3 – Cybersecurity and Trust;

- EUR 507 347 000 for Specific Objective 4 – Advanced Digital Skills;

- EUR 1 002 217 000 for Specific Objective 5 – Deployment and Best Use of Digital Capacities and Interoperability;

- **EUR 1 575 000 000 for Specific Objective 6 – Semiconductors**.

Chips Act

2022/0032(COD) - 31/01/2023 - Committee report tabled for plenary, 1st reading/single reading

The Committee on Industry, Research and Energy adopted the report by Dan NICA (S&D, RO) on the proposal for a regulation of the European Parliament and of the Council Establishing a framework of measures for strengthening Europe's semiconductor ecosystem (Chips Act).

The committee responsible recommended that the European Parliament's position adopted at first reading under the ordinary legislative procedure should amend the proposal as follows:

Subject matter

The proposed Regulation establishes a framework for strengthening the semiconductor sector at Union level, in particular through the following measures:

- establishment of the **Chips for Europe Initiative**;

- setting the criteria to recognise and to support first-of-a-kind Integrated Production Facilities, Open EU Foundries and **first-of-a-kind facilities** that foster the security of supply and the resilience of the semiconductor ecosystem and deployment of novel and innovative semiconductor technologies in the Union;

- setting up a coordination mechanism between the Member States and the Commission, for **mapping and monitoring the semiconductor value chain** and, where relevant, consulting stakeholders from the semiconductor supply and value chain as well as stakeholders from critical sectors that might be affected by disruptions to the supply of semiconductors;

- **developing crisis prevention and response tools** in the semiconductor supply chain shortages with a view to ensuring the internal market’s resilience and enabling the Union to play a stronger role at the global level.

Components and objectives of the Initiative

The general objective of the Initiative is to **increase the competitiveness and resilience of the Union's semiconductor ecosystem** by supporting technological capacity building research and innovation throughout the Union’s semiconductor supply and value chain and by enabling the development and deployment of cutting-edge and next generation semiconductor and semiconductor technologies for quantum chips and the development and innovation of established technologies. This is intended to reinforce the Union’s advanced design, systems integration and chips production capabilities, packaging, and manufacturing equipment as well as to contribute to achieving the twin digital and green transition, to improve quality employment, while strengthening the sustainability circular economy processes and addressing security needs and cybersecurity threats.

The Initiative should have **five operational objectives**:

- ***operational objective 1***: building up advanced design capacities for integrated semiconductor technologies;

- ***operational objective 2***: enhancing existing and developing new advanced pilot lines while ensuring geographical balance;

- ***operational objective 3***: building advanced technology and engineering capacities for accelerating the innovative development of cutting-edge and next generation quantum chips;

- ***operational objective 4***: creating a network of competence centres across the Union;

- ***operational objective 5***: undertaking activities, to be described collectively as ‘Chips Fund’ activities that ensure clear guidance and facilitate access to debt financing and equity by start-ups, scale-ups, and SMEs and other companies in the semiconductor value chain, through a blending facility under the InvestEU Fund and via the European Innovation Council.

European Chips Infrastructure Consortium

With a view to creating a pan-European ecosystem within the internal market where knowledge, expertise, resources and existing strengths are pooled and to accelerating implementation of the actions of the Initiative, it is necessary to provide an option of implementing some of the Initiative actions, in particular on pilot lines, through a new legal instrument, the European Chips Infrastructure Consortium (ECIC). Members proposed that the ECIC should be set up by at least three members, comprising Member States, public or private legal entities from at least three Member States, or a combination thereof, ensuring the geographically balanced representation.

Long-term strategic mapping and monitoring

The report suggested that the Commission should carry out a long-term strategic mapping of the Union's semiconductor value chain in cooperation with the national competent authorities, with the aim of **identifying early warning indicators**, of building knowledge and capacity to inform future industrial policy measures and assess the Union's strengths and weaknesses in the global semiconductor value chain. A coordinated approach to monitoring of the semiconductor value chains is needed to mitigate possible market disruptions.

International cooperation

According to Members, international cooperation with third countries is an important element to achieve a resilience of the Union's semiconductor ecosystem. Therefore, the Commission should pursue cooperation with relevant third countries on mutual support and benefits in the field of semiconductor supply, building on complementarities and interdependencies along the semiconductor supply chain, in accordance with international obligations.

New budget resources

The report stated that the amount of the financial resources dedicated to the Chips initiative should be drawn from the unallocated margins under the Multiannual Financial Framework (MFF) ceilings or mobilised through the non-thematic MFF special instruments. EUR 1.65 billion for the initiative under the Digital Europe Programme should be additional to the funding of existing objectives and should not reduce their financial envelope: the allocation of funds to the first five specific objectives should therefore be maintained, while an additional EUR 1.65 billion should be allocated to a new specific objective for the initiative.

Chips Act

2022/0032(COD) - 18/09/2023 - Final act

PURPOSE: to o strengthen Europe's semiconductor ecosystem (Chips Act).

LEGISLATIVE ACT: Regulation (EU) 2023/1781 of the European Parliament and of the Council establishing a framework of measures for strengthening Europe's semiconductor ecosystem and amending Regulation (EU) 2021/694 (Chips Act).

CONTENT: this Regulation on the Chips Act aims to **reduce the EU's vulnerabilities** and dependencies on foreign actors while reinforcing the EU's industrial base for chips, maximising future business opportunities and creating good-quality jobs. This will improve the **EU's security of supply, resilience, and technological sovereignty** in the field of chips.

The Regulation establishes a framework for strengthening the semiconductor ecosystem at Union level, in particular through the following measures:

Establishment of the Chips for Europe Initiative

The Chips for Europe Initiative reinforces Europe's technological leadership, by facilitating the transfer of knowledge from the lab to the fab, bridging the gap between research and innovation and industrial activities and by promoting the industrialisation of innovative technologies by European businesses.

The Initiative - established for the duration of the Multiannual Financial Framework 2021–2027 - will be supported by funding from Horizon Europe and the Digital Europe Programme, for a maximum indicative amount of **EUR 1.725 billion and EUR 1.575 billion**, respectively.

The Initiative has **five operational objectives**:

1. building up advanced design capacities for integrated semiconductor technologies;

2. enhancing existing and developing new **advanced pilot lines** across the Union to enable development and deployment of cutting-edge semiconductor technologies and next-generation semiconductor technologies;

3. building advanced technology and engineering capacities for accelerating the innovative development of cutting-edge quantum chips and associated semiconductor technologies;

4. establishing a network of **competence centres** across the Union by enhancing existing or creating new facilities;

5. undertaking activities, to be described collectively as **'Chips Fund'** activities, to facilitate access to debt financing and equity, including by providing clear guidance, in particular for start-ups, scale-ups, SMEs and small mid-caps in the semiconductor value chain, through a blending facility under the InvestEU Fund and via the European Innovation Council.

For the purpose of implementing actions funded under the Initiative, a legal entity may be established in the form of a European chips infrastructure consortium (ECIC).

A framework to ensure security of supply and resilience by attracting investment

The Regulation sets out the criteria for recognising and supporting pioneering **EU integrated production facilities and open foundries** that improve the security of supply and resilience of the EU semiconductor ecosystem.

An integrated production facility should meet the following requirements:

- have a clear positive impact with spill-over effects beyond the undertaking or Member State concerned, on the Union’s semiconductor value chain in the medium to long term, with a view to ensuring security of supply and resilience of the semiconductor ecosystem, including the growth of start-ups and SMEs, and contributing to the Union’s green and digital transitions;

- invest in continued innovation in the EU in order to achieve concrete progress in semiconductor technologies or to prepare for next-generation technologies;

- strengthening the EU's talent pool by developing and deploying educational and skills training and by increasing the pool of qualified and skilled workforce.

Recognition as one or another type of facility will allow access to fast-track licensing in Member States for the construction and operation of facilities.

The Commission may award a **‘Design Centre of Excellence’ label** to design centres established in the EU that significantly enhance the EU's capability in innovative chip design through their service offerings or through the development, promotion and strengthening of design skills and capabilities.

A crisis monitoring and response system

The Regulation provides for the establishment of a coordination mechanism between the Member States and the Commission for the **mapping** and monitoring of the EU semiconductor sector as well as for crisis prevention and response in case of semiconductor shortages and, where appropriate, consultation of stakeholders in the semiconductor sector.

Governance

The Regulation provides for the **creation of a European Semiconductor Board** to provide the Commission with advice, assistance and recommendations. It is composed of representatives of all Member States and chaired by a representative of the Commission.

ENTRY INTO FORCE: 21.9.2023.